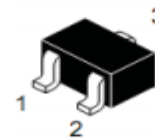
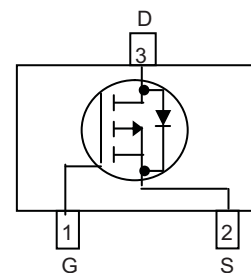


WPM3023
Single P-Channel, -30V, -3.9A, Power MOSFET
[Http://www.sh-willsemi.com](http://www.sh-willsemi.com)

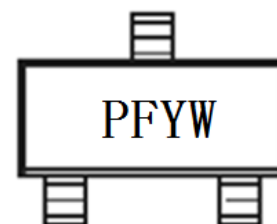
V_{DS} (V)	Typical $R_{DS(on)}$ (m Ω)
-30	37 @ $V_{GS}=-10V$
	50 @ $V_{GS}=-4.5V$


Descriptions

The WPM3023 is P-Channel enhancement MOS Field Effect Transistor. Uses advanced trench technology and design to provide excellent $R_{DS(on)}$ with low gate charge. This device is suitable for use in DC-DC conversion, power switch and charging circuit. Standard Product WPM3023 is Pb-free.

SOT-23

Pin configuration (Top view)
Features

- Trench Technology
- Supper high density cell design
- Excellent ON resistance
- Extremely Low Threshold Voltage
- Small package SOT-23



PF = Device Code
Y = Year
W = Week(A~z)

Applications

- DC/DC converters
- Power supply converters circuit
- Load/Power Switching for portable device

Marking
Order information

Device	Package	Shipping
WPM3023-3/TR	SOT-23	3000/Tape&Reel

Absolute Maximum ratings

Parameter		Symbol	10 s	Steady State	Unit
Drain-Source Voltage		V _{DS}	-30		V
Gate-Source Voltage		V _{GS}	±20		
Continuous Drain Current ^{a d}	T _A =25°C	I _D	-3.9	-3.3	A
	T _A =70°C		-3.1	-2.6	
Maximum Power Dissipation ^{a d}	T _A =25°C	P _D	1.2	0.9	W
	T _A =70°C		0.8	0.6	
Continuous Drain Current ^{b d}	T _A =25°C	I _D	-3.1	-2.8	A
	T _A =70°C		-2.5	-2.3	
Maximum Power Dissipation ^{b d}	T _A =25°C	P _D	0.8	0.7	W
	T _A =70°C		0.5	0.4	
Pulsed Drain Current ^c		I _{DM}	-15.6		A
Operating Junction Temperature		T _J	-55 to 150		°C
Lead Temperature		T _L	260		°C
Storage Temperature Range		T _{stg}	-55 to 150		°C

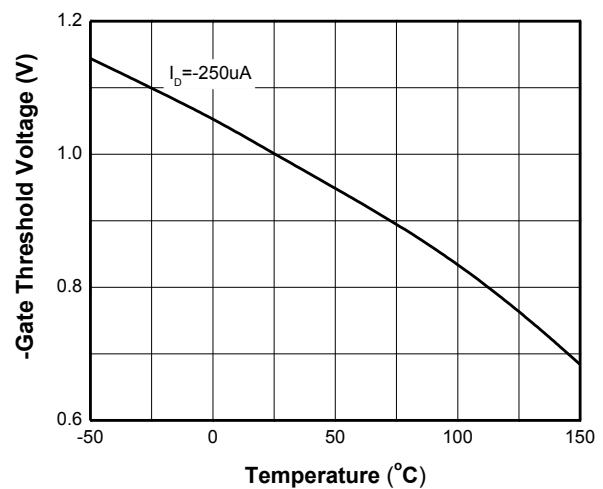
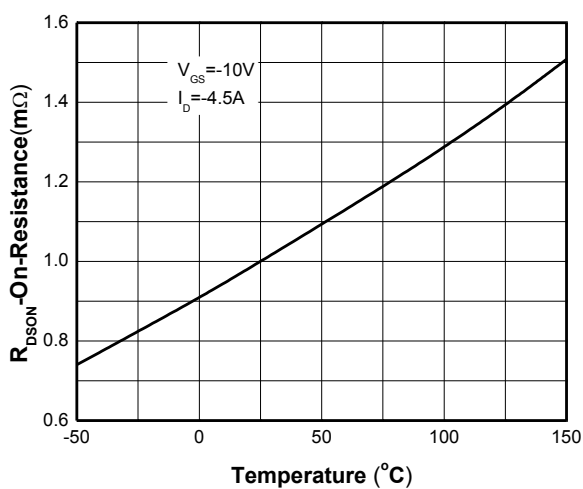
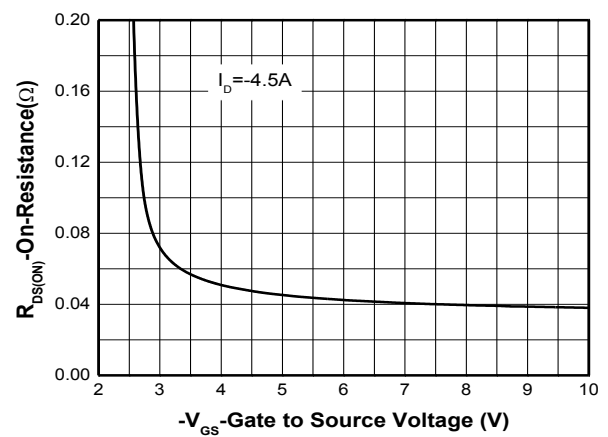
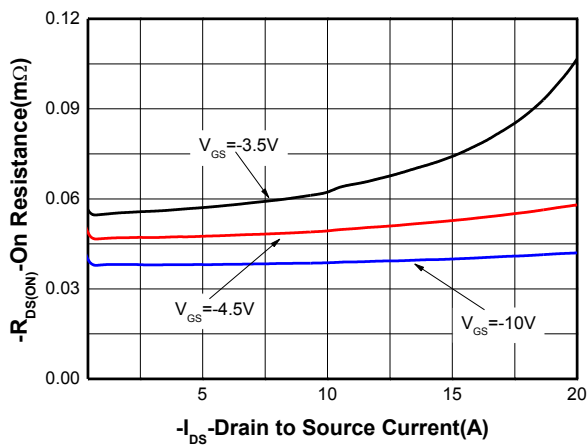
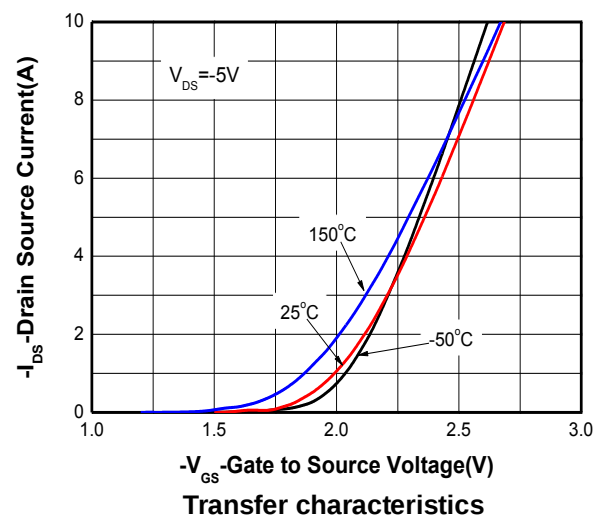
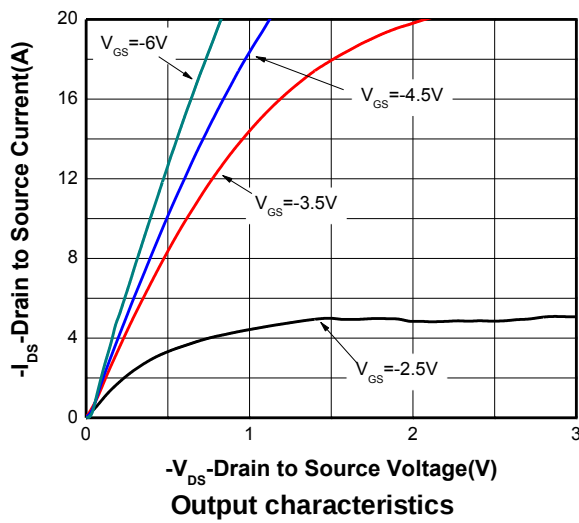
Thermal resistance ratings

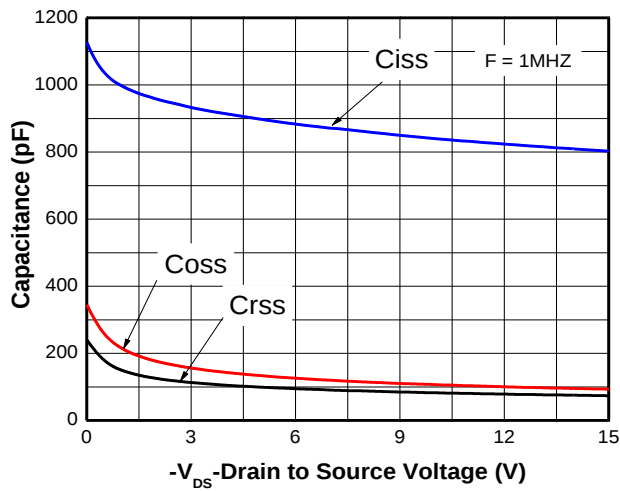
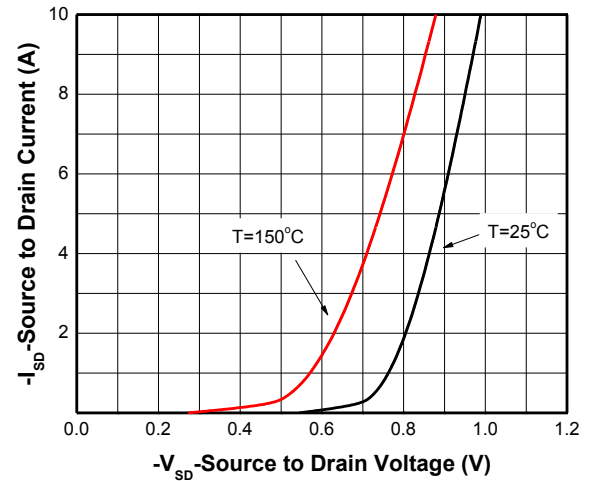
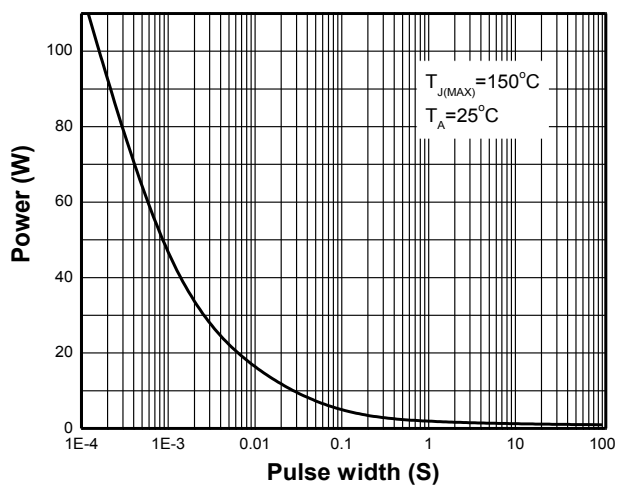
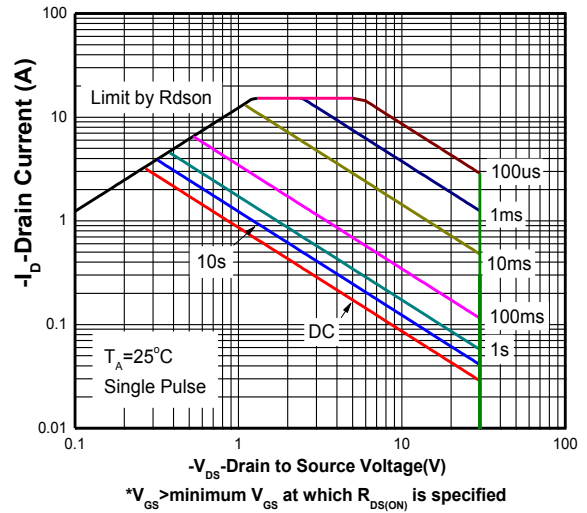
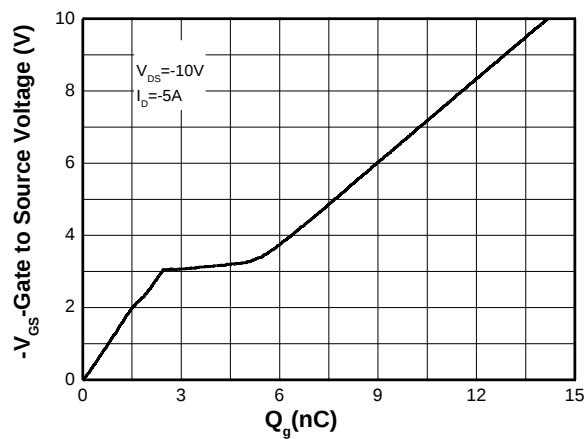
Parameter		Symbol	Typical	Maximum	Unit
Junction-to-Ambient Thermal Resistance ^a	$t \leq 10 \text{ s}$	$R_{\theta JA}$	84	102	$^{\circ}\text{C/W}$
	Steady State		120	145	
Junction-to-Ambient Thermal Resistance ^b	$t \leq 10 \text{ s}$	$R_{\theta JA}$	130	160	
	Steady State		145	190	
Junction-to-Case Thermal Resistance		$R_{\theta JC}$	60	75	

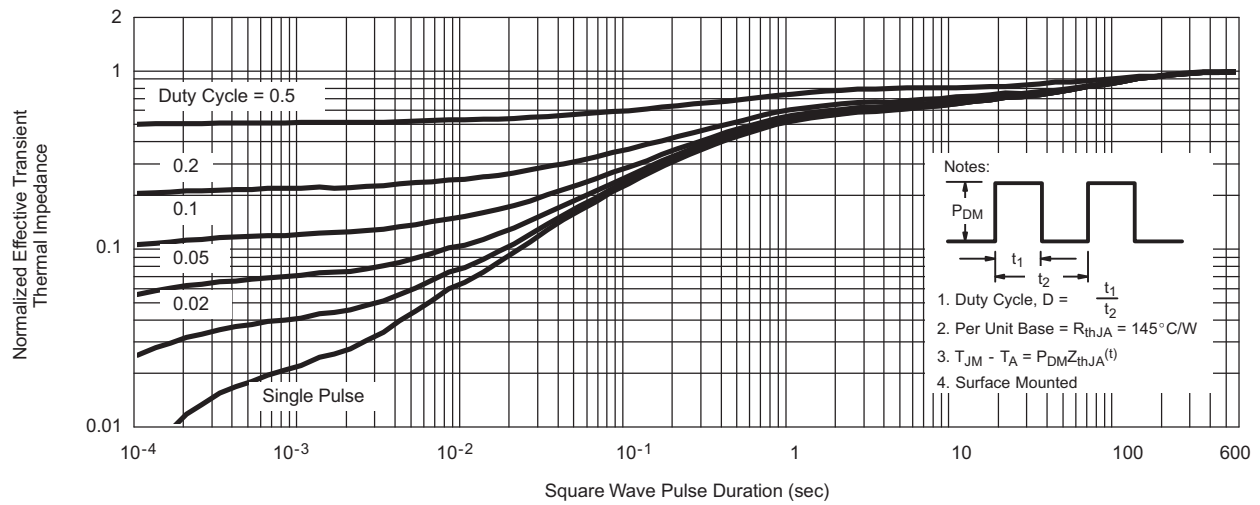
- Surface mounted on FR4 Board using 1 in sq pad size, 1oz Cu.
- Surface mounted on FR4 board using the minimum recommended pad size, 1oz Cu.
- Repetitive rating, pulse width limited by junction temperature, $t_p=10\mu\text{s}$, Duty Cycle=1%.
- Repetitive rating, pulse width limited by junction temperature $T_J(\text{MAX})=150^{\circ}\text{C}$.

Electronics Characteristics (Ta=25°C, unless otherwise noted)

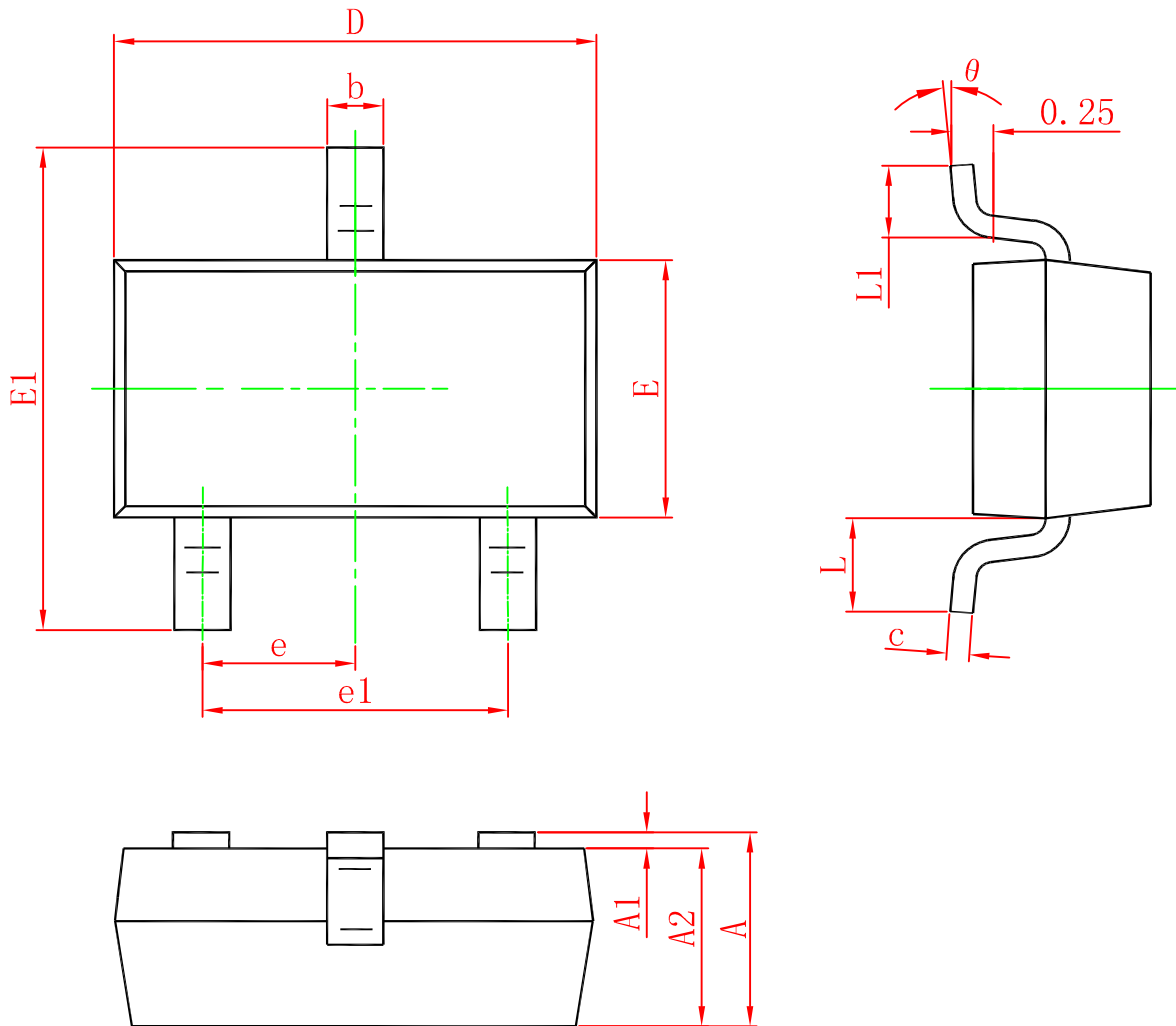
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
OFF CHARACTERISTICS						
Drain-to-Source Breakdown Voltage	BV _{DSS}	V _{GS} = 0 V, I _D = -250uA	-30			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-24V, V _{GS} = 0V			-1	uA
Gate-to-source Leakage Current	I _{GSS}	V _{DS} = 0 V, V _{GS} = ±20V			±100	nA
ON CHARACTERISTICS						
Gate Threshold Voltage	V _{GS(TH)}	V _{GS} = V _{DS} , I _D = -250uA	-1.0	-1.8	-3.0	V
Drain-to-source On-resistance	R _{DS(on)}	V _{GS} = -10V, I _D = -4.5A		37	54	mΩ
		V _{GS} =-4.5V, I _D = -4A		50	74	
Forward Transconductance	g _{FS}	V _{DS} = -5 V, I _D = -3.3A		4	7	S
CHARGES, CAPACITANCES AND GATE RESISTANCE						
Input Capacitance	C _{ISS}	V _{GS} = 0 V, f = 1.0MHZ, V _{DS} = -15 V		778		pF
Output Capacitance	C _{OSS}			85		
Reverse Transfer Capacitance	C _{RSS}			68		
Total Gate Charge	Q _{G(TOT)}	V _{GS} = -4.5 V, V _{DS} = -10 V, I _D =-5.0 A		6.8		nC
Threshold Gate Charge	Q _{G(TH)}			0.55		
Gate-to-Source Charge	Q _{GS}			2.5		
Gate-to-Drain Charge	Q _{GD}			2.1		
SWITCHING CHARACTERISTICS						
Turn-On Delay Time	td(ON)	V _{GS} = -10 V, V _{DD} =-15 V, I _D =-4A, R _G =6Ω		11.2		ns
Rise Time	tr			4.7		
Turn-Off Delay Time	td(OFF)			50		
Fall Time	tf			8		
BODY DIODE CHARACTERISTICS						
Forward Voltage	V _{SD}	V _{GS} = 0 V, I _S = -1A	-0.6	-0.75	-1.2	V

Typical Characteristics (Ta=25°C, unless otherwise noted)



Capacitance

Body diode forward voltage

Single pulse power

Safe operating power

Gate Charge Characteristics



Transient thermal response (Junction-to-Ambient)

Package outline dimensions
SOT-23


Symbol	Dimensions In Millimeters	
	Min.	Max.
A	0.900	1.150
A1	0.000	0.100
A2	0.900	1.050
b	0.300	0.500
c	0.080	0.150
D	2.800	3.000
E	1.200	1.400
E1	2.250	2.550
e	0.950 (Typ.)	
e1	1.800	2.000
L	0.550 (Typ.)	
L1	0.300	0.500
θ	0°	8°